REVISIONS							
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED				
A	Add figure 4. Technical changes to 1.3, 1.4, table I, and table II. Change in terminal connections. Change VSPN to case outline 2. Editorial changes throughout. mlp	89-09-05	Michael A. Frye				
В	Changes in accordance with NOR 5962-R108-92 tvn	92-01-10	Monica L. Poelking				
С	Changes in accordance with NOR 5962-R116-93. tvn	93-03-26	Monica L. Poelking				
D	Add package CDFP4-F16. Use new boilerplate. Ijs	98-02-04	Raymond Monnin				
E	Modified Figure 4 to be consistent with Table I. Ijs	98-08-17	Raymond Monnin				

The original first page of this drawing has been replaced.

REV															
SHEET															
REV		1													
SHEET															
REV STATUS	REV	E	E	E	E	Е	E	Е	E	E	E	E	E	E	
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13	
PMIC N/A	PREPARED BY Monica L. Poe	elking				DI	FFFN	SF SI	IPPI	V CF	NTFF	COL	IIMR	iie	
STANDARD MICROCIRCUIT DRAWING	CHECKED BY Monica L. P	oelking			DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216										
THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS	APPROVED BY Michael A. f				MIC	CROC	CIRC	UIT, E	DIGIT	-AL, 1	ECL,	BINA	ARY T	ΓΟ 1-	8
AND AGENCIES OF THE DEPARTMENT OF DEFENSE	DRAWING APP	ROVAL	DATE		DE	COD	ER, L	OW,	MON	IOLI	THIC	SILI	CON		
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					SHE	ET		1	OF	13					

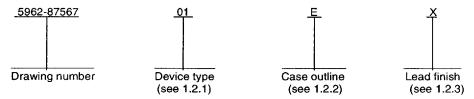
DSCC FORM 2233
APR 97
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5962-E460-98

## 1. SCOPE

1.1 Scope. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.

1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 <u>Device type(s)</u>. The device type(s) identify the circuit function as follows:

Device type Generic number Circuit function 01 10H561 Binary to 1-8 decoder (low)

1.2.2 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
E	GDIP1-T16 or CDIP2-T16	16	Dual -in-line
F	GDFP2-F16 or CDFP3-F16	16	Flat package
X	CDFP4-F16	16	Flat-package
2	CQCC1-N20	20	Square chip carrier

1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

Supply voltage range (VEE) .....

1.3 Absolute maximum ratings.

Supply voltage range (VEE)	-8.0 V dc to 0.0 V dc
Input voltage range	-5.2 V dc to 0.0 V dc
Storage temperature range	-65°C to +165°C
Lead temperature (soldering, 10 seconds)	+300°C
Junction temperature (T <sub>J</sub> )	+165°C
Maximum power dissipation (P <sub>D</sub> )	520 mW
Thermal resistance, junction-to-case (O <sub>JC</sub> )	See MIL-STD-1835

1.4 Recommended operating conditions.

Supply voltage range (Vcc)	
Ambient operating temperature range(T <sub>A</sub> )	+1.98 V dc to +2.02 V dc
Minimum high level input voltage (V <sub>IH</sub> ):	00 0 10 1 120 0
$T_A = +25^{\circ}C$	-0.780 V dc
$T_A = +125^{\circ}C$	-0.650 V dc
$T_A = -55^{\circ}C$	-0.840 V dc
Maximum low level input voltage (V <sub>IL</sub> )	-1.950 V dc

-5.46 V dc minimum to -4.94 V dc maximum

2

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-87567
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000	-	REVISION LEVEL	SHEET

DSCC FORM 2234

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## 2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbooks</u>. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

#### **SPECIFICATION**

#### **DEPARTMENT OF DEFENSE**

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

#### **STANDARDS**

### **DEPARTMENT OF DEFENSE**

MIL-STD-883 - Test Method Standard Microcircuits.

MIL-STD-973 - Configuration Management.

MIL-STD-1835 - Interface Standard For Microcircuit Case Outlines.

#### **HANDBOOKS**

### DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).

MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.
  - 3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
  - 3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-87567
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL E	SHEET 3

DSCC FORM 2234 APR 97

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- 3.2.3 Truth table. The truth table shall be as specified on figure 2.
- 3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.
- 3.2.5 Test circuit and switching waveforms. The test circuit and switching waveforms shall be as specified on figure 4.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 <u>Marking</u>. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.
- 3.6 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 Notification of change. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.
- 3.9 <u>Verification and review</u>. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
  - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.
- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A, B, C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-87567
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL E	SHEET 4

DSCC FORM 2234 APR 97

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T <sub>A</sub> ≤+125°C unless otherwise specified		Group A subgroups	Limits		Unit		
						Min	Max		
Cases E, F, 2 and X		Quiescen	t tests <u>1</u> /						
			V <sub>IH</sub>	V <sub>IL</sub>					
High level output voltage	Vон	Outputs terminated	-0.780	-1.950	1	-1.010	-0.780	٧	
		through 100Ω to	-0.650	-1.950	2	-0.860	-0.650		
		-2 V.	-0.840	-1.950	3	-1.060	-0.840		
Low level output voltage	VoL	V <sub>CC</sub> = 0.0 V	-0.780	-1.950	1	-1.950	-1.580	٧	
		V <sub>EE</sub> = -5.2 V <u>2</u> /	-0.650	-1.950	2	-1.950	-1.535		
			-0.840	-1.950	3	-1.950	-1.610		
High level threshold	VOHA		-1.110	-1.480	1	-1.010	-0.780	٧	
output voltage			-0.960	-1.465	2	-0.860	-0.650		
			-1.160	-1.510	3	-1.060	-0.840		
Low level threshold	VOLA		-1.110	-1.480	1	-1.950	-1.580	٧	
output voltage			-0.960	-1.465	2	-1.950	-1.535		
			-1.160	-1.510	3	-1.950	-1.610		
Power supply drain	iee	V <sub>EE</sub> = -5.46 V			1	-76		mA	
current 3/		Vcc = 0.0 V			2, 3	-84			
High level input current	l <sub>IH</sub>	V <sub>IH</sub> = -0.780 V at +25	s°C		1		275	μА	
		-0.650 V at +1	25°C		2, 3		465		
		-0.840 V at -55	5°C						
Low level input current	1 <sub>IL</sub>	V <sub>EE</sub> = -4.940 V <u>3</u> /			1,3	0.5		μА	
		V <sub>IL</sub> = -1.950 V			2	0.3		, FE'	
		$V_{CC} = +0.0 \text{ V}$							
Functional tests		See 4.3.1c			7, 8A, 8B				

See footnotes at end of table.

STANDARD
MICROCIRCUIT DRAWING
DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216-5000

SIZE
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SP62-87567

REVISION LEVEL
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5

DSCC FORM 2234 APR 97

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TABLE I. Electrical performance characteristics.

Test	Symbol	Condit -55°C ≤ T <sub>A</sub> unless otherwi	4≤+125°C	ed	Group A subgroups	Lim	nits	Unit
				<del></del>	<u> </u>	Min	Max	
Cases E, F and X		DC ra	pid test cor	nditions 4	<u></u>			
			ViH	VIL				
High level output voltage	Vон	Outputs terminated	-0.802	-1.950	1	-1.030	-0.802	V
		through 100Ω to	-0.674	-1.950	2	-0.882	-0.674	
		-2 V.	-0.864	-1.950	3	-1.082	-0.864	<u> </u>
Low level output voltage	Vol	V <sub>CC</sub> = 0.0 V	-0.802	-1.950	1	-1.950	-1.587	V
		V <sub>EE</sub> = -5.2 V <u>2</u> /	-0.674	-1.950	2	-1.950	-1.542	1
			-0.864	-1.950	3	-1.950	-1.617	<u>L</u>
High level threshold	VoHA	1	-1.130	-1.487	1	-1.030	-0.802	V
output voltage		1	-0.982	-1.472	2	-0.882	-0.674	•
			-1.182	-1.517	3	-1.082	-0.864	L
Low level threshold	VOLA	1	-1.121	-1.487	1	-1.950	-1.587	V
output voltage		1	-0.972	-1.472	2	-1.950	-1.542	I
			-1.172	-1.517	3	-1.950	-1.617	<u></u>
Power supply drain	IEE	V <sub>EE</sub> = -5.46 V			1	-75		mA
current 3/		V <sub>CC</sub> = 0.0 V		!	2, 3	-83	<u> </u>	<u> </u>
High level input current	Ін	V <sub>IH</sub> = -0.802 V at +25	5°C	!	1	1 '	260	μА
	'	-0.674 V at +12	25°C	1	2, 3	1 '	450	1
	· [ '	-0.864 V at -55	5°C	1	1	f '	1	1
Low level input current	I <sub>IL</sub>	V <sub>EE</sub> = -4.94 V <u>3</u> /			1,3	0.5		μА
		V <sub>CC</sub> = 0.0 V		!	2	0.3	1	1
	<u> </u> '	V <sub>IL</sub> = -1.950		!	l!	I'	l	ı
_Functional tests		See 4.3.1c			7, 8A, 8B			I

See footnotes at end of table.

STANDARD
MICROCIRCUIT DRAWING

DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216-5000

SIZE
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SP62-87567

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6

DSCC FORM 2234 APR 97

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TABLE I.	Electrical	performance	characteristics.
	LICOU IOUI	pontonnance	Gialacteristics.

Test	Symbol	Conditions -55°C ≤ T <sub>A</sub> ≤+125°C unless otherwise specified		-55°C ≤ T <sub>A</sub> ≤+125°C Group A Limits		-55°C ≤ T <sub>A</sub> ≤+125°C Group A Limits		Limits		Unit
						Min	Max			
Case 2		DC rapid test cor	nditions <u>4</u>	/						
			ViH	VIL						
High level output voltage	VoH	Outputs terminated	-0.809	-1.950	1	-1.037	-0.809	V		
		through 100Ω to	-0.682	-1.950	2	-0.889	-0.682			
		-2 V.	-0.872	-1.950	3	-1.089	-0.872			
Low level output voltage	VoL	V <sub>CC</sub> = 0.0 V	-0.809	-1.950	1	-1.950	-1.589	V		
		V <sub>EE</sub> = -5.2 V <u>2</u> /	-0.682	-1.950	2	-1.950	-1.545			
		]	-0.872	-1.950	3	-1.950	-1.620			
High level threshold	VOHA		-1.137	-1.489	1	-1.037	-0.809	V		
output voltage	1		-0.989	-1.475	2	-0.889	-0.682			
			-1.189	-1.520	3	-1.089	-0.872			
Low level threshold	VOLA		-1.137	-1.489	1	-1.950	-1.589	٧		
output voltage			-0.989	-1.475	2	-1.950	-1.545			
	ļ		-1.189	-1.520	3	-1.950	-1.620			
Power supply drain	IEE	V <sub>EE</sub> = -5.46 V			1	-75		mA		
current 3/	ļ	V <sub>CC</sub> = 0.0 V		2, 3	-83					
High level input current	l <sub>IH</sub>	VIH = -0.809 V at +25	5°C		1 1		260	μΑ		
		-0.682 V at +1	25°C		2, 3		450			
		-0.872 V at -55	5°C							
Low level input current	l <sub>IL</sub>	V <sub>EE</sub> = -4.94 V <u>3</u> /			1, 3	0.5		μА		
		Vcc = 0.0 V			2	0.3				
···		V <sub>IL</sub> = -1.950				!				
Functional tests		See 4.3.1c	-		7, 8A, 8B					

See footnotes at end of table.

STANDARD
MICROCIRCUIT DRAWING
DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216-5000

SIZE
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SIZE
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SP62-87567

REVISION LEVEL
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7

DSCC FORM 2234 APR 97

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## TABLE I. <u>Electrical performance characteristics</u> - Continued.

Test	Test Symbol Conditions $-55^{\circ}C \le T_{C} \le +125^{\circ}C$ unless otherwise specified		-	Group A subgroups	Limits		Unit
					Min	Max	
Cases E, F, 2 and X		AC tests					
Transition time	t <sub>TLH</sub> ,	V <sub>EE</sub> = -2.94 V	Ē <sub>0</sub>	9	0.55	1.50	ns
	tTHL	V <sub>CC</sub> = 2.0 V	-0	10	0.60	1.60	
		C <sub>L</sub> ≤ 5 pF		11	0.55	1.50	
Propagation delay time	t <sub>PHH1</sub> ,	Load all outputs through	A, B, C	9	0.65	2.20	ns
A, B, C to Y	tpLL1,	$100\Omega$ to ground.		10	0.70	2.40	
	t <sub>PHL1</sub> ,	See figure 4.		11	0.60	2.20	
	t <sub>PLH1</sub>						
Propagation delay time	t <sub>PHH2</sub> ,		Ēo,	9	0.80	2.30	ns
ENABLE to Y	tPLL2		E <sub>1</sub>	10	0.90	2.60	
	t <sub>PHL2</sub> ,		E <sub>1</sub>	11	0.80	2.30	
	t <sub>PLH2</sub>						
Functional tests		See 4.3.1c		7, 8A, 8B			

- 1/ The quiescent limits are determined after a device has reached thermal equilibrium. This is defined as the reading taken with the device in a socket with ≥ 500 LFPM of +25° C, +125° C or -55° C (as applicable) air blowing on the unit in a transverse direction with power applied for at least 4 minutes before the reading is taken. This method was used for theoretical limit establishment only. All devices shall be tested to the delta V (rapid test) conditions specified herein. The rapid test method is an equivalent method of testing quiescent conditions.
- 2' The high and low level output current varies with temperature and shall be calculated using the following formulas:  $I_{OH} = (-2 \text{ V} \text{V}_{OH})/100\Omega$  and  $I_{OL} = (-2 \text{ V} \text{V}_{OL})/100\Omega$ .
- 3/ The IEE limits, although specified in the minimum column, shall not be exceeded in magnitude, as a maximum value.
- 4/ The dc rapid test forcing functions and limits are used for all dc testing. These limits are determined for each device type based on the power dissipation and package type. The rapid test (delta V) limits and forcing functions are skewed allowing rapid testing to be performed at standard temperatures without the addition of delta T's.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-87567
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		E	8

DSCC FORM 2234 APR 97

9004708 0038532 659

Case outlines	E	F, X	2	
Terminal number	Terminal symbol			
1	V <sub>CC1</sub>	Y4	NC	
2	Ē <sub>0</sub>	С	V <sub>CC1</sub>	
3	Y3	Ē <sub>1</sub>	Ē <sub>0</sub>	
4	Y2	V <sub>CC2</sub>	<b>Y3</b>	
5	Y1	V <sub>CC1</sub>	Y2	
6	YO	_ <b>E</b> ₀	NC	
7	Α	Y3	Y1	
8	V <sub>EE</sub>	Y2	Y0	
9	В	Y1	Α	
10	<b>Y</b> 7	Y0	VEE	
11	Y6	A	NC	
12	Y5	VEE	В	
13	Y4	В	<b>Y</b> 7	
14	С	Y7	Y6	
15	Ē <sub>1</sub>	Y6	Y5	
16	V <sub>CC2</sub>	Y5	NC	
17			Y4	
18			С	
19			Ē <sub>1</sub>	
20			V <sub>CC2</sub>	

NC = No connection

FIGURE 1. Terminal connections.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87567
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL E	SHEET 9

DSCC FORM 2234 APR 97

	able outs		Inputs					Out	puts			i
E1	E0	С	В	Α	YO	Y1	Y2	Y3	Y4	Y5	Y6	<b>Y</b> 7
	L L L	L L H H	LLHHLL	L H L H L	L H H H H	H	H H H H H	H H H H H	H H H L H	H H H H L	H H H H H	H H H H
L	L X H	H H X	H X X	L X X	   H   H   H	H H H	H H H	: H H H	: H H H H	H H H T	: H H	H L H

X = Don't care

FIGURE 2. Truth table.

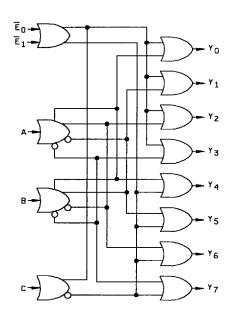
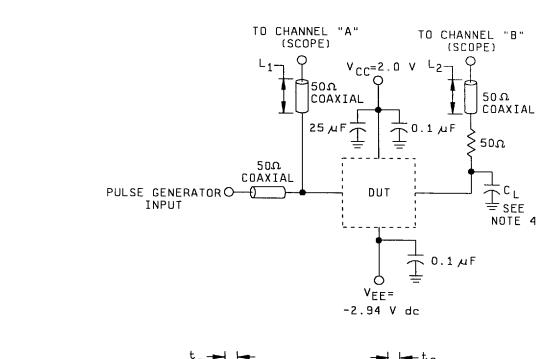


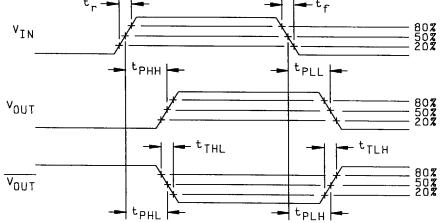
FIGURE 3. Logic diagram.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-87567
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL E	SHEET 10

DSCC FORM 2234 APR 97

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# NOTES:

- 1. All other outputs loaded 100  $\Omega$  to ground.
- 2:1 divider may be used.
- 3.  $L_1 = L_2$ : Matched for equal time delay.
- 4. C<sub>L</sub> (test jig) ≤ 5 pF.
   5. Pulse generator characteristics:

PRR = 1 MHz;  $t_r$  and  $t_f$  = 2.0  $\pm$  0.2 ns (20% to 80%), duty cycle = 50%.

FIGURE 4. Test circuit and switching waveforms.

STANDARD MICROCIRCUIT DRAWING	SIZE <b>A</b>		5962-87567
DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
COLUMBUS, OHIO 43216-5000		E	11

DSCC FORM 2234 **APR 97** 

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1*, 2, 3, 7*, 8A, 8B, 9
Group A test requirements (method 5005)	1, 2, 3, 7, 8A, 8B, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

<sup>\*</sup> PDA applies to subgroup 1 and 7.

4.3 <u>Quality conformance inspection</u>. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

# 4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 7, 8A and 8B shall include verification of the truth table specified on figure 2 herein.

## 4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
  - (1) Test condition D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
  - (2)  $T_A = +125^{\circ}C$ , minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

# 5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-87567
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000		REVISION LEVEL E	SHEET <b>12</b>

DSCC FORM 2234 APR 97

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## 6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0525.
- 6.5 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0674.
- 6.6 <u>Approved sources of supply</u>. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING

DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216-5000

SIZE <b>A</b>		5962-87567
	REVISION LEVEL E	SHEET 13

DSCC FORM 2234 APR 97

9004708 0038537 130

#### STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 98-08-17

Approved sources of supply for SMD 5962-87567 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

		· · · · · · · · · · · · · · · · · · ·
Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8756701EA	0EU86	AS10H561C16/883C
5962-8756701FA	<u>3/</u>	10H561/BFAJC
5962-87567012A	0EU86	AS10H561EC20/883C
5962-8756701XA	0EU86	AS10H561F16/883C

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ No longer available from the approved source of supply

Vendor CAGE \_\_number\_

Vendor name and address

0EU86

Austin Semiconductor Inc. 8701 Cross Park Dr. Austin, TX 78754-4566

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.

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